Method for Stripping a Product Substrate from a Carrier Substrate

Abstract

The invention relates to a method for stripping a product substrate (7) from a carrier substrate (3) which is connected to the product substrate (7) by an interconnect layer (6) with the following steps, especially the following sequence:

- application of solvents (9) to one flat side (3o) of the carrier substrate (3) facing away from the interconnect layer (6),
- flow of a throughflow portion of the solvent (9) through the carrier substrate (3),
- at least partial detachment of the interconnect layer (6), predominantly by the throughflow portion and
- stripping of the product substrate (7) from the carrier substrate (3).

Figure 2